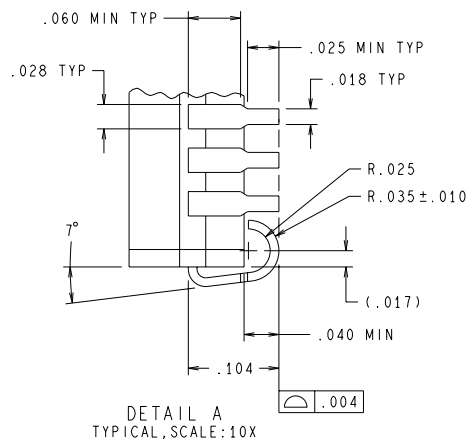
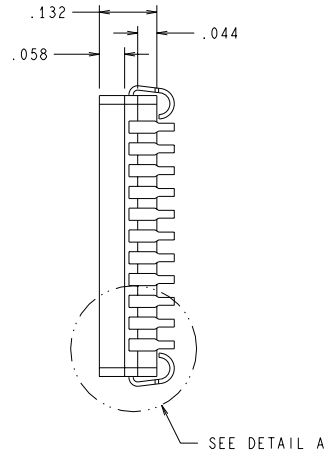
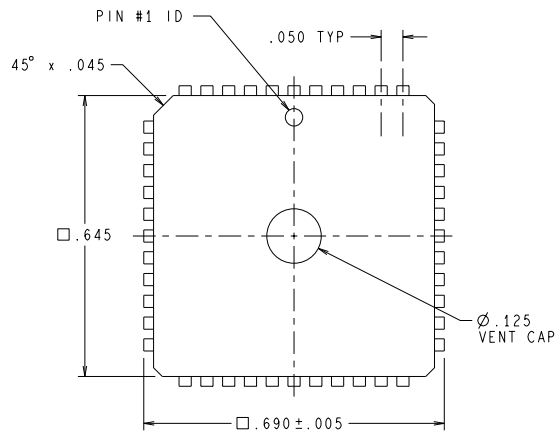


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10667	11/08/94	KES/



DIMENSIONS ARE IN INCHES

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
- TOLERANCE OF LEAD FRAME TO PACKAGE BODY IS
± .020 MAXIMUM.
- REFERENCE INDY DRAWING 04-044-YQ-001 REV B,
DATED 09/14/92.

APPROVALS	DATE	 2900 Semiconductor dr., Santa Clara, CA 95052-8090 METAL LEADED CHIP CARRIER, J-BEND, .050 LD PITCH, 44 LD, CAVITY UP			
DRAWN KURT SINCERBOX	11/08/94				
DFTG. CHK.					
ENGR. CHK.					
 INCH (MM)		SCALE N/A	SIZE C	DRAWING NUMBER MKT-AA44A	REV A
		DO NOT SCALE DRAWING		SHEET 1 of 1	